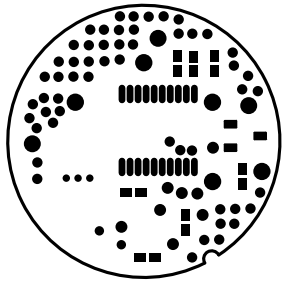
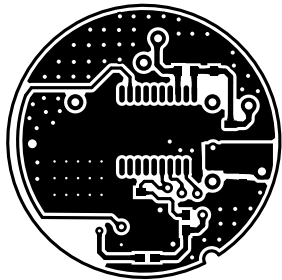


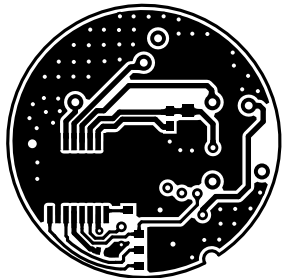
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01619	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01619		
PLOT NAME = Top Overlay	GENERATED : 3/6/2018	3:59:34 PM	TEXAS INSTRUMENTS



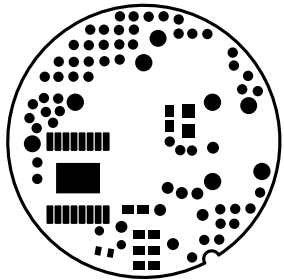
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01619	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01619		
PLOT NAME = Top Solder Mask	GENERATED : 3/6/2018	3:59:36 PM	TEXAS INSTRUMENTS



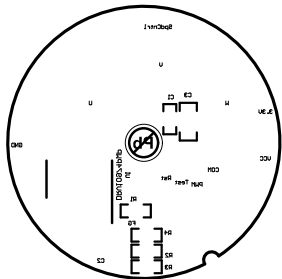
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01619	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01619		
PLOT NAME = Top Layer	GENERATED : 3/6/2018	3:59:38 PM	TEXAS INSTRUMENTS



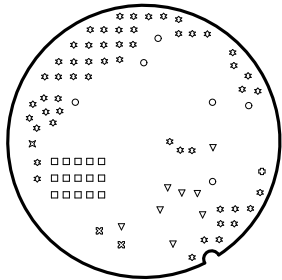
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01619	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01619		
PLOT NAME = Bottom Layer	GENERATED : 3/6/2018	3:59:40 PM	TEXAS INSTRUMENTS



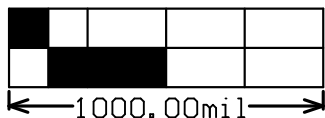
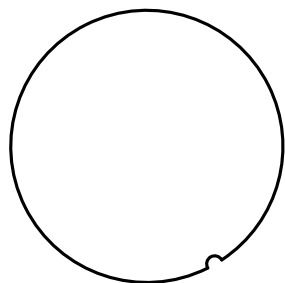
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01619	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01619		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/6/2018	3:59:42 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01619	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01619		
PLOT NAME = Bottom Overlay	GENERATED : 3/6/2018	3:59:44 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01619	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01619		
PLOT NAME = Drill Drawing	GENERATED : 3/6/2018	3:59:46 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01619	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01619		
PLOT NAME = Board Dimensions	GENERATED : 3/6/2018	3:59:48 PM	TEXAS INSTRUMENTS



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